

(19) United States

(12) Patent Application Publication (10) Pub. No.: US 2024/0178838 A1 AGRAWAL et al.

May 30, 2024 (43) **Pub. Date:**

(54) AUDIO INTERFACE PHYSICAL LAYER

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(21) Appl. No.: 18/058,988

(22) Filed: Nov. 28, 2022

Publication Classification

(51) Int. Cl. H03K 19/00 (2006.01)G06F 3/16 (2006.01)H03K 5/01 (2006.01)H03K 19/21 (2006.01) H04R 3/00 (2006.01)(2006.01) H04R 3/12

(52) U.S. Cl. CPC H03K 19/0002 (2013.01); G06F 3/162 (2013.01); H03K 5/01 (2013.01); H03K 19/21

(2013.01); H04R 3/005 (2013.01); H04R 3/12 (2013.01); H03K 2005/00013 (2013.01)

(57)**ABSTRACT**

An integrated circuit (IC) includes a tristatable output buffer having a control input. The IC includes an input buffer having a buffer output. The IC further includes a delay circuit having a delay circuit input, a first delay circuit output, and a second delay circuit output. The delay circuit input is coupled to the buffer output. The IC also includes a tristate circuit coupled to the first delay circuit output and to the second delay circuit output. The tristate circuit having a tristate circuit output coupled to the control input.

